

ABSTRACT

A microelectromechanical device package and a low-stress inducing method for packaging a microelectromechanical device are disclosed in this invention. The microelectromechanical device is accommodated within a cavity comprised by a first package substrate and a second substrate, wherein a third substrate is disposed between and bonded to both the microelectromechanical device lower semiconductor substrate and the package bottom substrate. The first and second package substrates are then bonded so as to package the microelectromechanical device inside.